

---

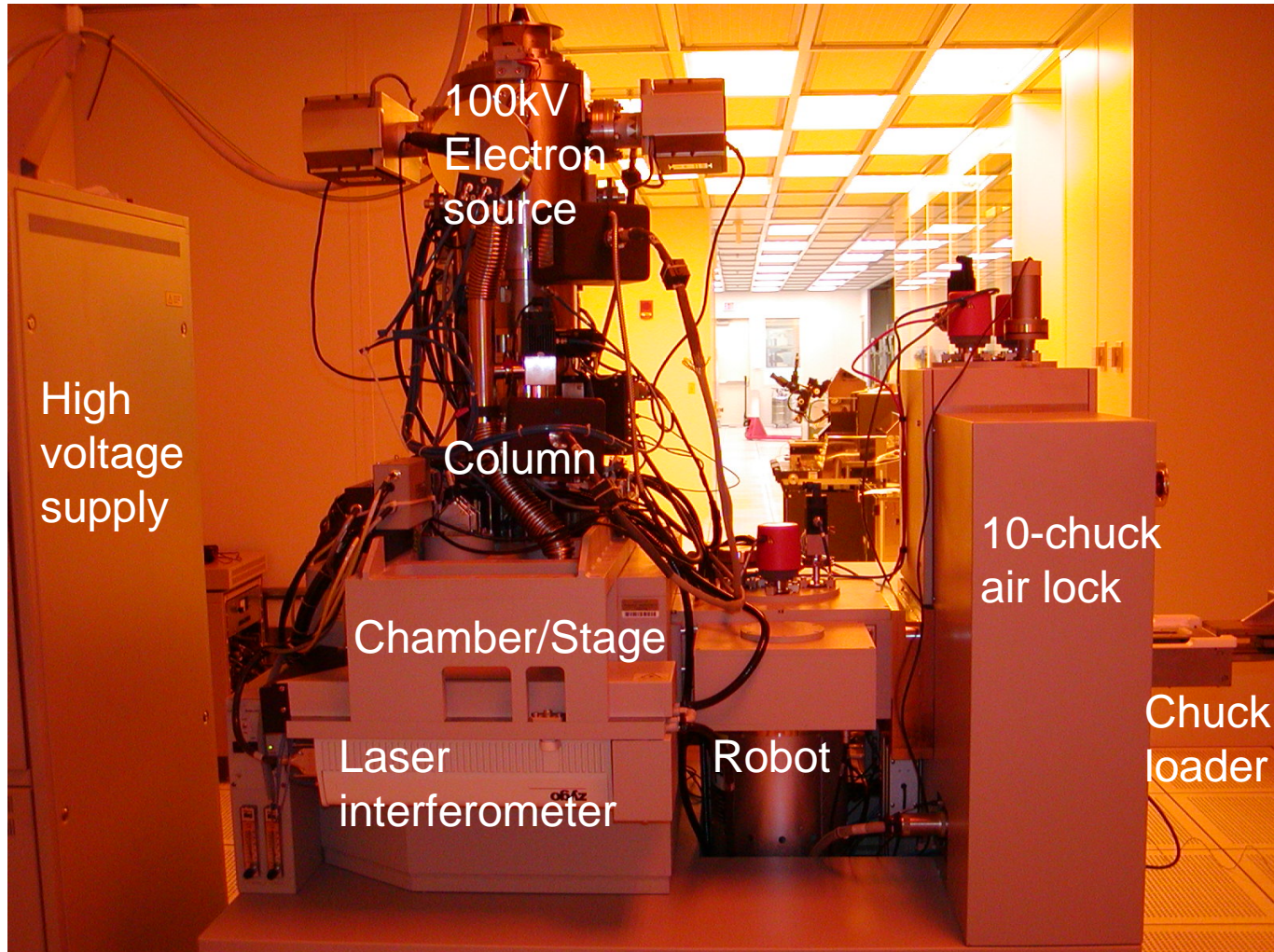
# Nanometer Scale Patterning and Processing

Spring 2016

## Lecture 19

### Vector Beam Performance and Operation

# The Raith VB6 UHR-EWF EBL tool



# Environmental Control for high stability



Water chiller ( $\pm 0.01$  °C)



Temperature stabilized column, chamber and air lock

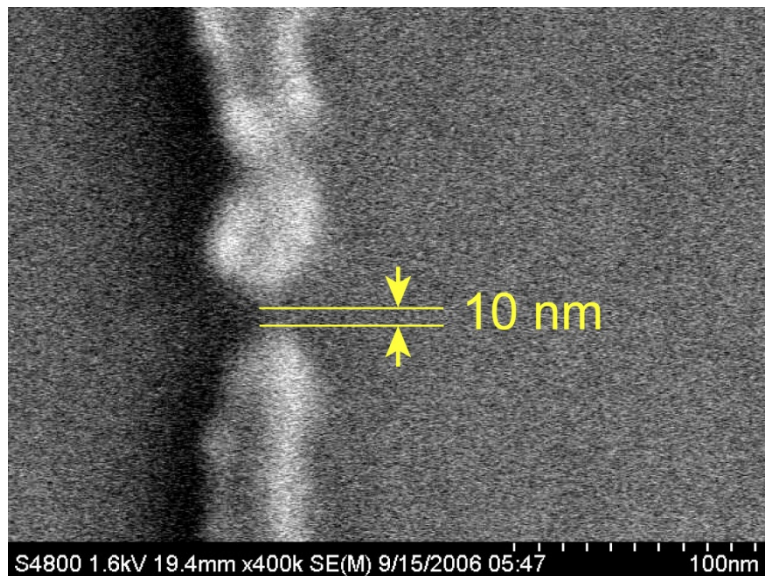
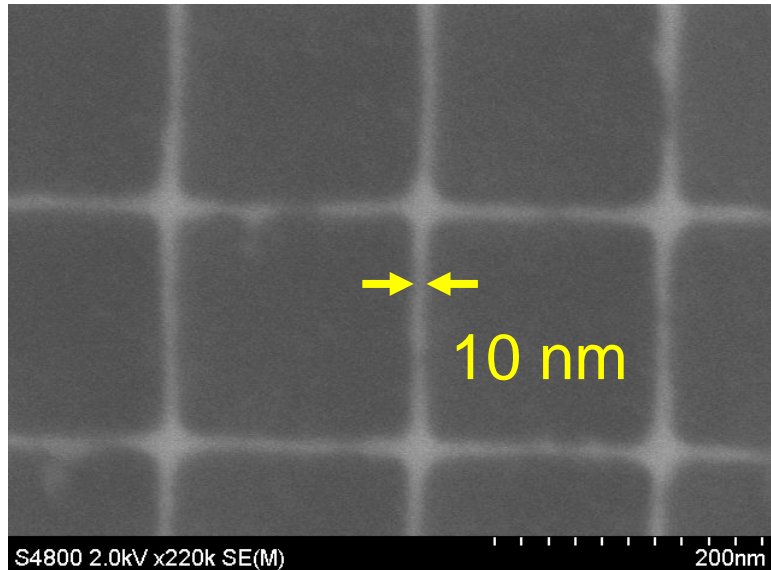


Active vibration isolation



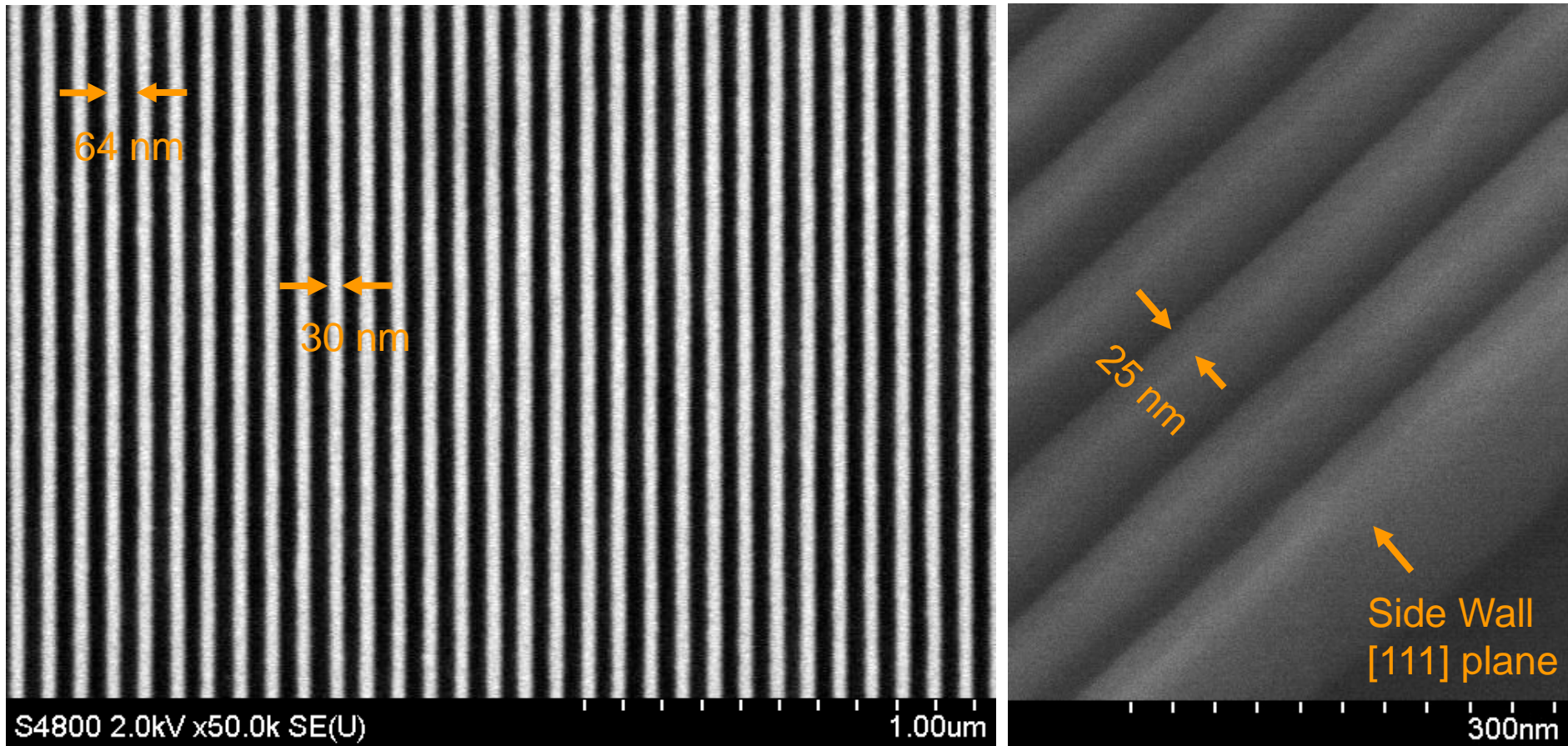
EM field cancellation system

# Performance of the E-beam tool



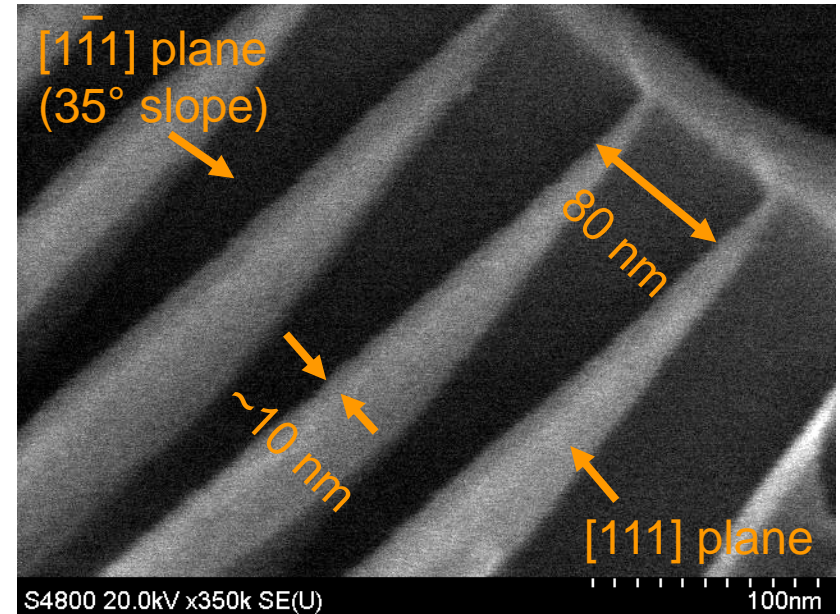
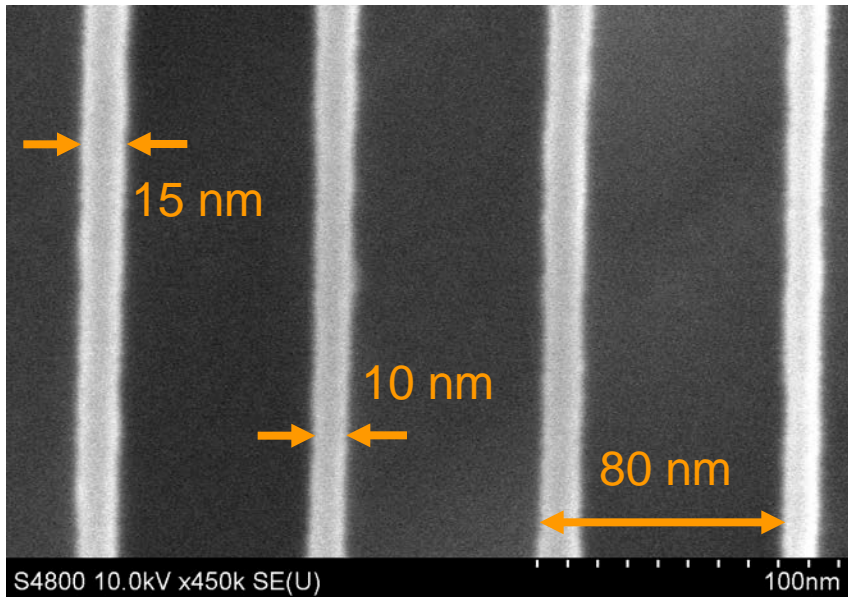
- Resolution:  
10 nm or less
- Intra-field distortion:  
< 10 nm
- Stitching error: < 20 nm
- Overlay: < 25 nm
- Maximum field size:  
1.3 mm
- Maximum deflection speed: 25 MHz
- Maximum wafer size:  
200 mm (8 inch)
- Beam position stability:  
< 70 nm/hr

# 64 nm Pitch Grating in 110 Si

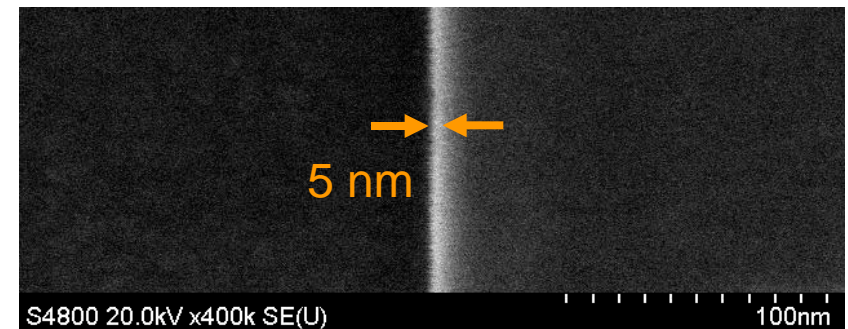


- 45 nm thick HSQ as etch mask, 2 min. etch in 60 °C KOH.
- Good alignment to the crystal orientation.
- High contrast in top view indicates etch into Si substrate

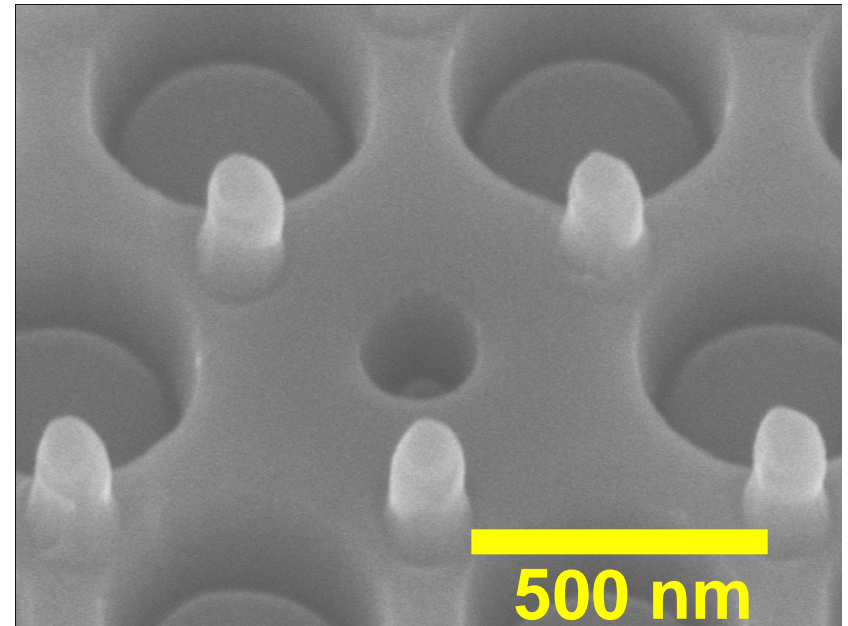
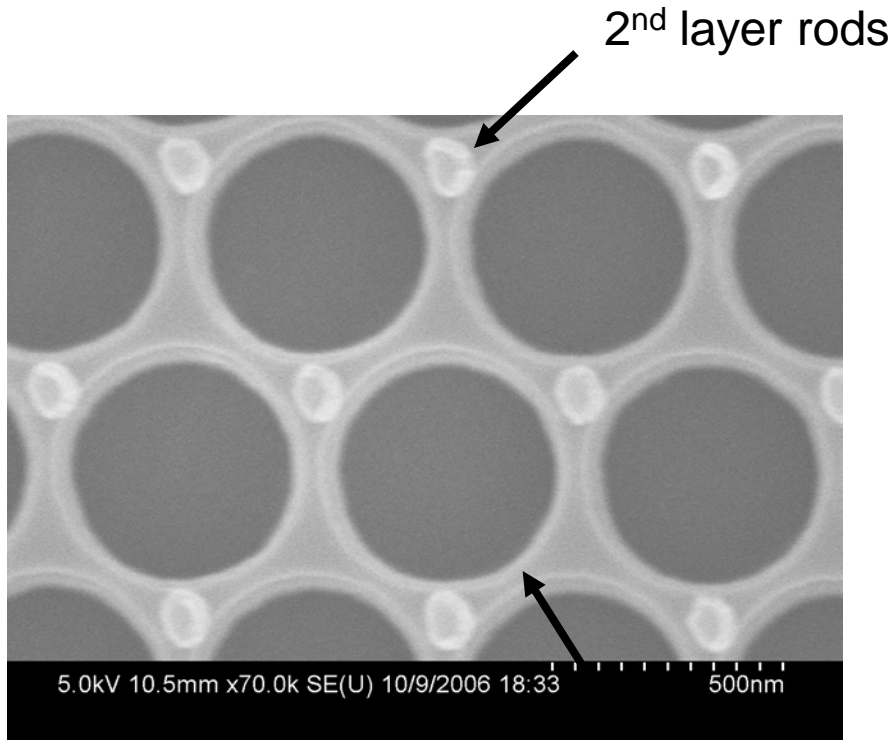
# ~10 nm lines at 80 nm pitch



- Linewidth variation around 5 nm
- Smooth sidewalls preserved down to 10 nm lines.
- Isolated line at 5 nm.



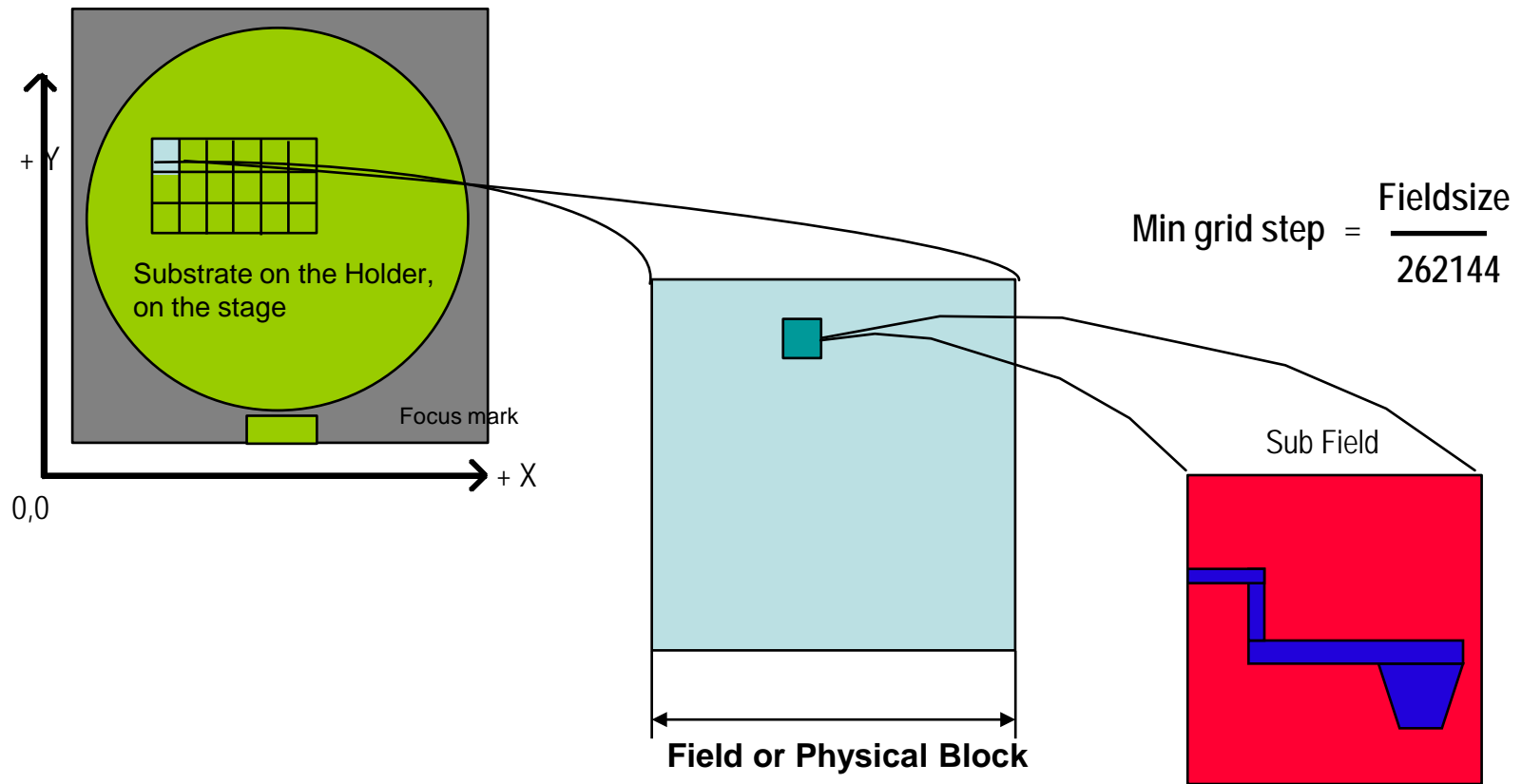
# Excellent Alignment Capability



Top view

Tilted view

# Writing Strategy (Wide Field)



1. Stage moved to position of Field or Physical Block within pattern.

2. Sub-field positioned by Main deflection scan

3. Subfield area scanned by "Trapezium scan coils"



# Dose Control

---

The correct dose is achieved by setting the time duration that the beam dwells at each exposure point within the pattern.

This time duration is determined by the frequency of the **DOSE CLOCK**.

A clock frequency of 1MHz sets the exposure time per pixel to 1 micro-second.

A pattern shape containing 10,000,000 exposure points will take 1 Second to expose with a clock set to 10MHz.

The maximum frequency possible is 25MHz

The Dose required for correct exposure depends on the

- Resist Sensitivity

- Field Size

- Beam Current

- EHT

- Variable Resolution factor (VRU)

- Electron beam back-scatter

# Corrections

---

## Corrections are applied in real time for:

### Main field scan corrections

- Scale, rotation & keystone over the main field

### Trapezium field scan corrections

- Scale, rotation & keystone over the main field

### Focus and Astigmatism

- Focus and Stigmatism correction over main field
- Focus correction for each stage position dependant on substrate height

### Beam Error Feedback

- Scale and Rotation corrections dependant on mainfield deflection.

### Height

- Real time or Pre-map corrections of focus and deflection scan rotation

### Stage Position

- Beam Error Feedback
- Magnetic effect
- Orthogonality
- Machine mapping